



Test Research, Inc. (TRI), a leading test and inspection systems provider for the electronics manufacturing industry, returns to Nepcon China 2014 with a powerful and cost-effective product lineup that encompasses a full range of solutions for inspecting and testing PCB assemblies. Test Research, Inc. invites you to visit **Booth No. B-1G40, from April 23-25, 2014** at **Shanghai World Expo & Exhibition Convention Center (Hall 1)** for an on-site demonstration of the following systems.



TR7007 SII Plus 3D SPI

- Ultimate 3D SPI Solution
- Industry Leading Inspection Speed
- Super High Resolution and Accuracy
- Ultra Low Bridge Detection
- Smart 5-step Easy Programming
- Closed Loop Integration



TR5001E INLINE ICT

- Automatic Load and Unload
- Fast Insertion Mechanism
- Conforms to SMEMA Standards
- Dual Stage Press Unit
- Powerful Boundary Scan Test Solutions
- Easy to Use On-board Programming Software
- Digital 1:1 Driver/ Receiver per Pin Architecture
- QDI Quick Release Interface



TR7500 SIII 3D AOI

- Total Coverage 2D + Multi Angle 3D AOI
- True 3D Profile Measurement
- 5 High Resolution Color Cameras
- Fully Automated Easy Programming
- High Performance Design for Automotive and HDI



TR518 SII INLINE MDA

- Compact MDA for Small Boards up to 1024 Points
- Cost Effective Inline Platform
- High Speed Analog Testing
- Modular MDA Configuration
- Intelligent Board Handling for Damage Prevention
- Bypass Conveyor for Multiple Inline Testers



TR7700 SIII AOI

- High Speed Multi-Phase Inspection
- 10 μm 60 cm^2/sec
- 15 μm 120 cm^2/sec
- Fully Automated Intelligent Programming
- Auto-tuning Intelligent Automated Conveyor System



TR5001T SII TINY ICT

- World's Most Powerful Tiny ICT
- Best Cost Cutting Solution
- Multi-ICT Parallel Testing
- Boundary Scan Test
- Serial Device Programming
- Advanced Analog and Digital Testing with Programmable DUT Power Supplies



TR7700 SIII DT AOI

- Industry Leading 4-phase Desktop AOI
- Fully Automated Intelligent Programming
- High Inspection Performance & Accuracy
- Fine-Pitch / 01005 Component Ready
- Designed for Large Board Inspection up to 510 x 460 mm



TR7600LL SII 3D AXI

- High-speed Oversize Inline 3D X-ray Inspection
- Board Size up to 1000 x 660 mm
- BGA, PoP, Press-fit, PTH, QFN, Inspection
- Automated CAD-based or Manual Programming with Auto Tuning
- Multiple Resolutions in One Program
- BlockScan 3D Slice Imaging

YMS LITE

- Defect Image Analysis & Reporting
- SPI, Pre/Post-reflow AOI & AXI Integration
- Centralized Alarm Management